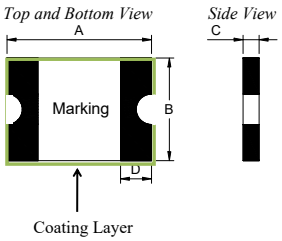
1、Physical Dimensions(size of 0805)

Unit:mm

Part Number	A*		B*		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
KPSML200TC	2.00	2.70	1.20	1.90	0.40	0.80	0.20	F

* Dimension is measured after coating



2、Electrical Characteristics

● Vmax= 6Vdc ● Imax= 50A

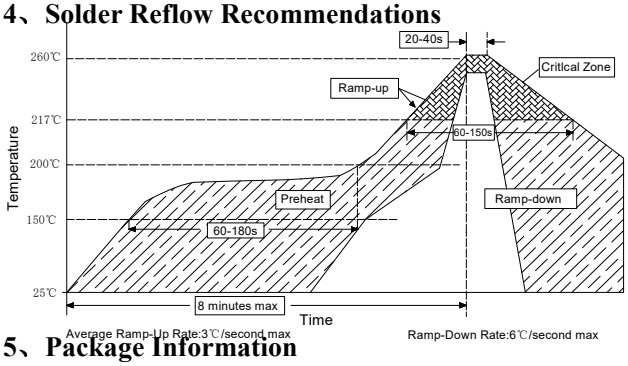
Model	Hold current and Trip current (AMPS)				Time To Trip (Sec.)		Pd_{typ} （W）	R_{min} (Ω)	$R1_{max}$ (Ω)
KPSML200TC	25℃		60℃		10.0A @ 25℃		25℃,6V	25℃	25℃
	I-hold	I-trip	I-hold	I-trip	Min	Max	Max	0.006	0.055
	2.00	4.00	1.33	2.66	-	2.0	1.20		

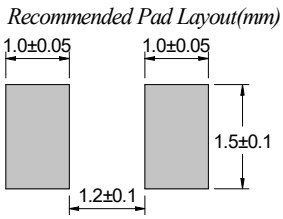
I-hold: Holding Current: maximum current at which the device will not trip in 25℃ or 60℃ still air.
I-trip: Tripping Current minimum current at which the device will trip in 25℃ or 60℃ still air.
V_{max}: Maximum voltage device can withstand without damage at rated current.
I_{max}: Maximum fault current device can withstand without damage at rated voltage.
Time To Trip: Maximum time to trip(s) at assigned current.
Pd_{typ}: Rated working power.
R_{min}: Minimum resistance of device prior to trip at 25℃.
$R1_{max}$: Maximum resistance of device is measured one hours post reflow at 25℃.
Noted: All electrical function test is conducted after PCB mounted.

3、Thermal Derating

KPSML200TC	Maximum ambient operating temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
Hold Current(A)	2.70	2.35	2.18	2.00	1.65	1.42	1.33	1.12	0.80
Trip Current(A)	5.40	4.70	4.36	4.00	3.30	2.84	2.66	2.24	1.60

4、Solder Reflow Recommendations





Notes:If reflow temperatures exceed the recommended profile,devices may not meet the performance requirements.

5、Package Information

Packing quantity:4500PCS/Reel

Note:Reel packaging per EIA-481-1 standard